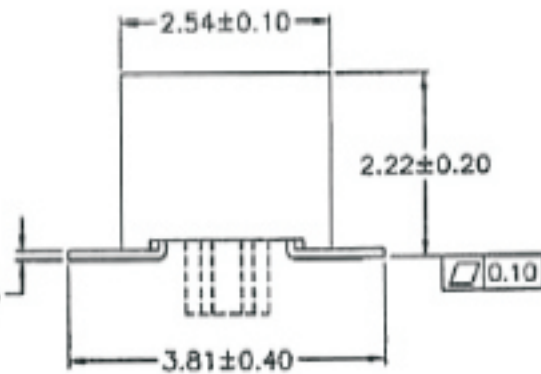
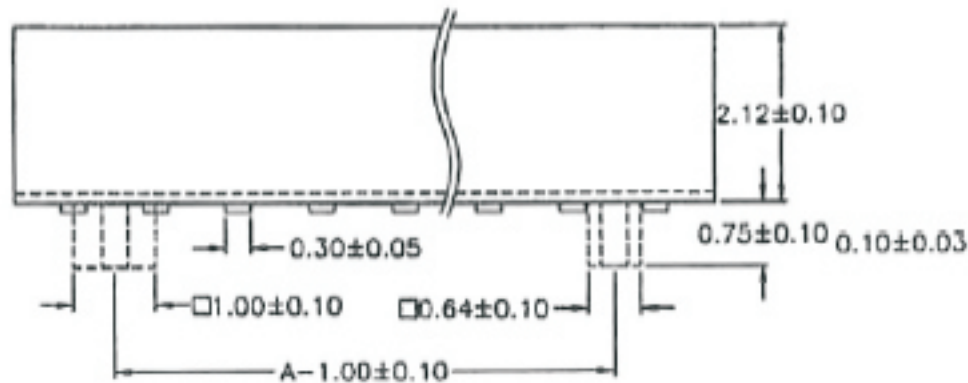
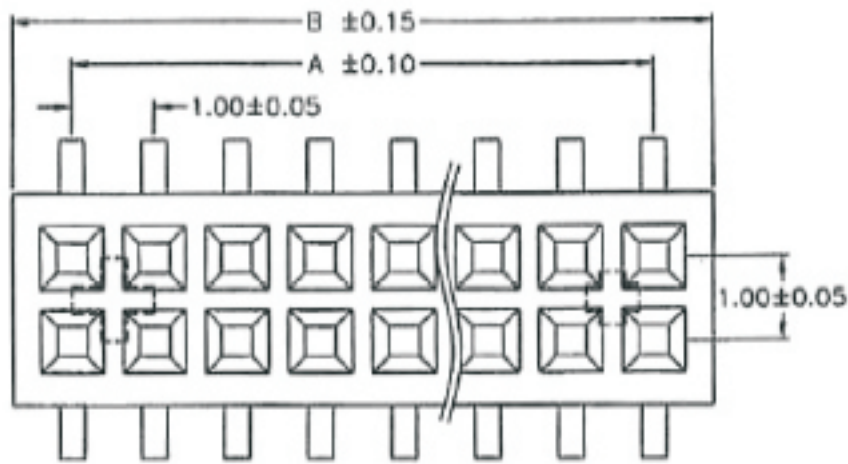
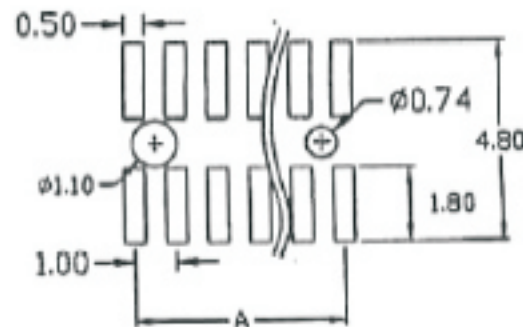


No. of Contacts	DIMENSIONS	
	A	B
10	4.00	5.43
12	5.00	6.43
14	6.00	7.43
16	7.00	8.43
18	8.00	9.43
20	9.00	10.43
22	10.00	11.43
24	11.00	12.43
26	12.00	13.43
28	13.00	14.43
30	14.00	15.43
32	15.00	16.43
34	16.00	17.43
36	17.00	18.43
38	18.00	19.43
40	19.00	20.43
42	20.00	21.43
44	21.00	22.43
46	22.00	23.43
48	23.00	24.43
50	24.00	25.43
52	25.00	26.43
54	26.00	27.43
56	27.00	28.43
58	28.00	29.43
60	29.00	30.43
62	30.00	31.43
64	31.00	32.43
66	32.00	33.43
68	33.00	34.43
70	34.00	35.43
72	35.00	36.43
74	36.00	37.43
76	37.00	38.43
78	38.00	39.43
80	39.00	40.43
82	40.00	41.43
84	41.00	42.43
86	42.00	43.43
88	43.00	44.43
90	44.00	45.43
92	45.00	46.43
94	46.00	47.43
96	47.00	48.43
98	48.00	49.43
100	49.00	50.43



Recommended P.C.Board SMD Layout



REV	ECN. NO.	APP	DATE
A	EDIÇÃO INICIAL		

SPECIFICATIONS

Current Rating: 1 Amp
 Insulator resistance: 5000 Megohms Min.
 Contact resistance: 20 m ohm Max.
 Dielectric withstanding: AC 500 V
 Operating Temperature: -40' ~ +105'C
 Contact Material: Phosphor Bronze.
 Insulator Material: L.C.P.,UL 94V-0
 Standard : Gold flash all over nickel
 Retention Force : 200 g Min Per Pin.
 Insertion Force : 150 g Min Per Pin.
 Separator Force : 25 g Min Per Pin.

HOW TO ORDER:
MAT[][D][R][][S][B]D[V][][R]
1 2 3 4 5 6 7 8

- 1- Nr. of Ways
Double Row: 2 to 80
- 2- Row Version:
(D)-Double Row
- 3- Pin Style
(R)-180°
- 4- Terminal Plating:
(E)-Sn
(D)-FLASH Au
(F)-0,38um Au
(G)-0,76um Au
(C)-0,38um Au/Sn
(H)-0,76um Au/Sn
- 5- Pitch:
(B)-1,0mm x 1,0mm
- 6- Profile:
(V)-2,10mm
- 7- Options:
(T)-Tube Packing
(Y)-With Locating Peg (Tube)
- 8- (R) RoHS Compliant

		MATRIX TECNOLOGIA IND. E COM. LTDA.	
		UNIT mm	SCALE
TOLERANCE: ±0.25			
		MATL	CHK. BY
		DWG. NO.	DR. BY DIEGO